

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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MI1206L501R-10

UNCONTROLLED DOCUMENT

PHYSICAL DIMENSIONS:

(C)

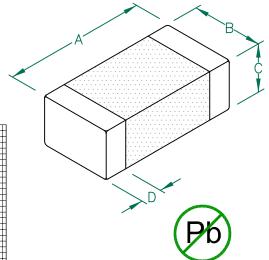
IMPEDANCE

± 0.20 [.008] A 3.20 [.126]

± 0.20 [.008] B 1.60 [.063]

C 1.10 [.043] ± 0.20 [.008]

D 0.51 [.020] ± 0.25 [.010]



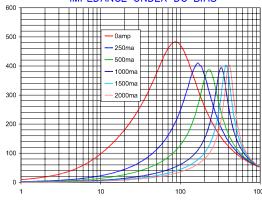
ELECTRICAL CHARACTERISTICS:								
Z @ 100M (Ω)	1Hz	DCR $\left(\begin{array}{c}\Omega\end{array}\right)$	Rated Current					
Nominal	500							
Minimum	375							
Maximum	625	0.060	2000 mA					

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL.
- 2. TERMINATION FINISH IS 100% TIN.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. OPERATING TEMP. RANGE: -40°C~+125°C. (INCLUDING SELF-HEATING)

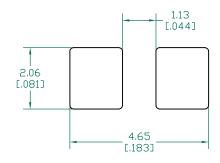
IMPEDANCE UNDER DC BIAS

Z vs FREQUENCY



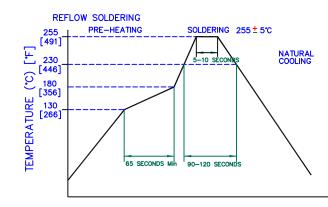
FREQUENCY (MHz)

LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 (.030) to this dimension)

RECOMMENDED SOLDERING CONDITIONS



		Z , R, A	ND X vs. I	FREQUENCY	
	600				
IMPEDANCE (12)	500				
	400				
	300		Z		
	200		A R		
	100				
	1	10	100	1000	1000

FREQUENCY (MHz)

					_				
DIMENSIONS ARE IN mm [INCHES].			This print is the property of Lair	d					
				Tech. and is loaned in confidence					7,
				subject to return upon request and with the understanding that no			2		1
				copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.			Laird		
9	E UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	g QU	PROJECT/PART NUMBER:	RE	v	PART TY	PE:	DRAWN BY:
1				MI1206L501R-10		ח	co-	FIRE	ТМВ
С	ADD OPERATING TEMPERATURE	06/23/11	WEI	WII1200L3011K 10		٦	- 00		"""
В	UPDATE COMPANY LOGO	08/25/08	JRK	DATE: 03/26/04 S	CALE:	N.	TS	SHEET:	•
Α	ORIGINAL DRAFT	03/26/04	TMB	CAD 4	00L s		<u>'`</u>	2	of 2
REV	DESCRIPTION	DATE	INT	MI1206L501R-10-D		_	-	_	01 2

AGILENT E4991A RF Impedance/Material Analyzer HP 16194A Test Fixture. TEST REF. 3227